

2009. 10. 26

Perspectives on ReRAM technologies

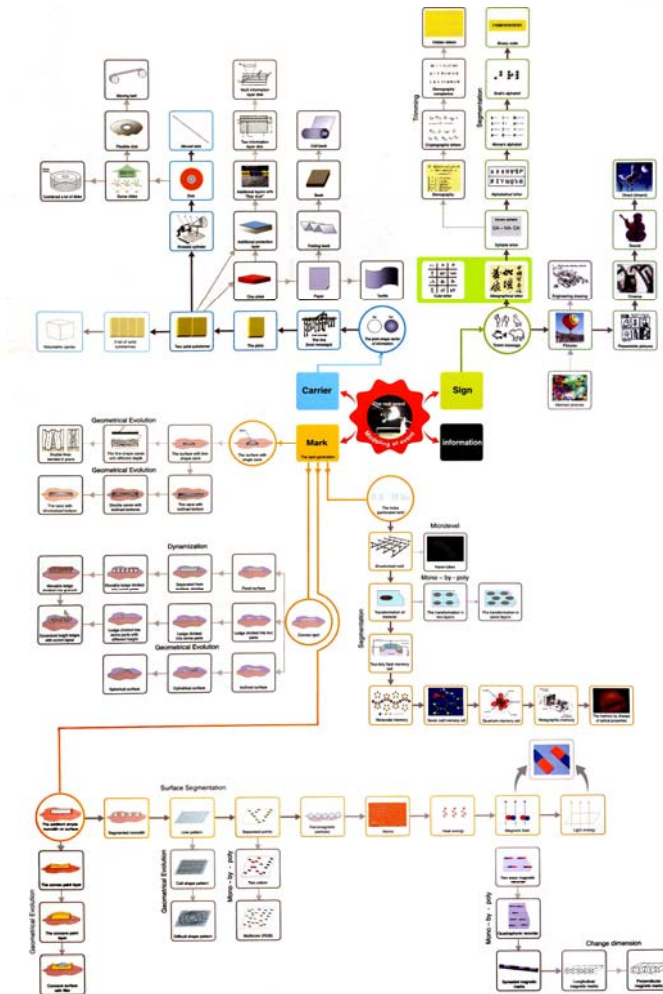
IN K. YOO

SAMSUNG ADVANCED INSTITUTE OF TECHNOLOGY

- **EVOLUTION PATTERNS OF PRODUCTS**
- **CAN WE FORECAST FUTURE PRODUCTS?**
- **PERSPECTIVES ON RERAM TECHNOLOGIES**
- **A SWITCHING MECHANISM IN RERAM**
- **RESEARCH SUGGESTIONS**

Patterns of product evolution

Evolution Tree of information storage

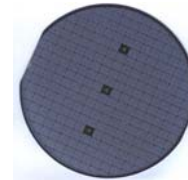


Evolution patterns

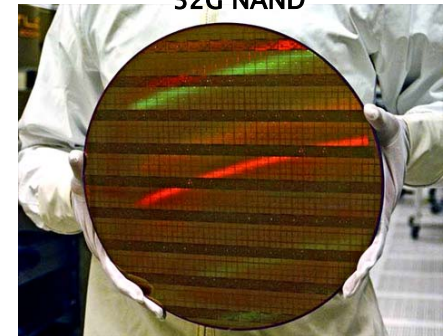
- Dynamization
- Mono-Bi-Poly pattern
- Segmentation
- Geometric evolution
- Substance introduction

⇒ **Increase in entropy**

1G NAND



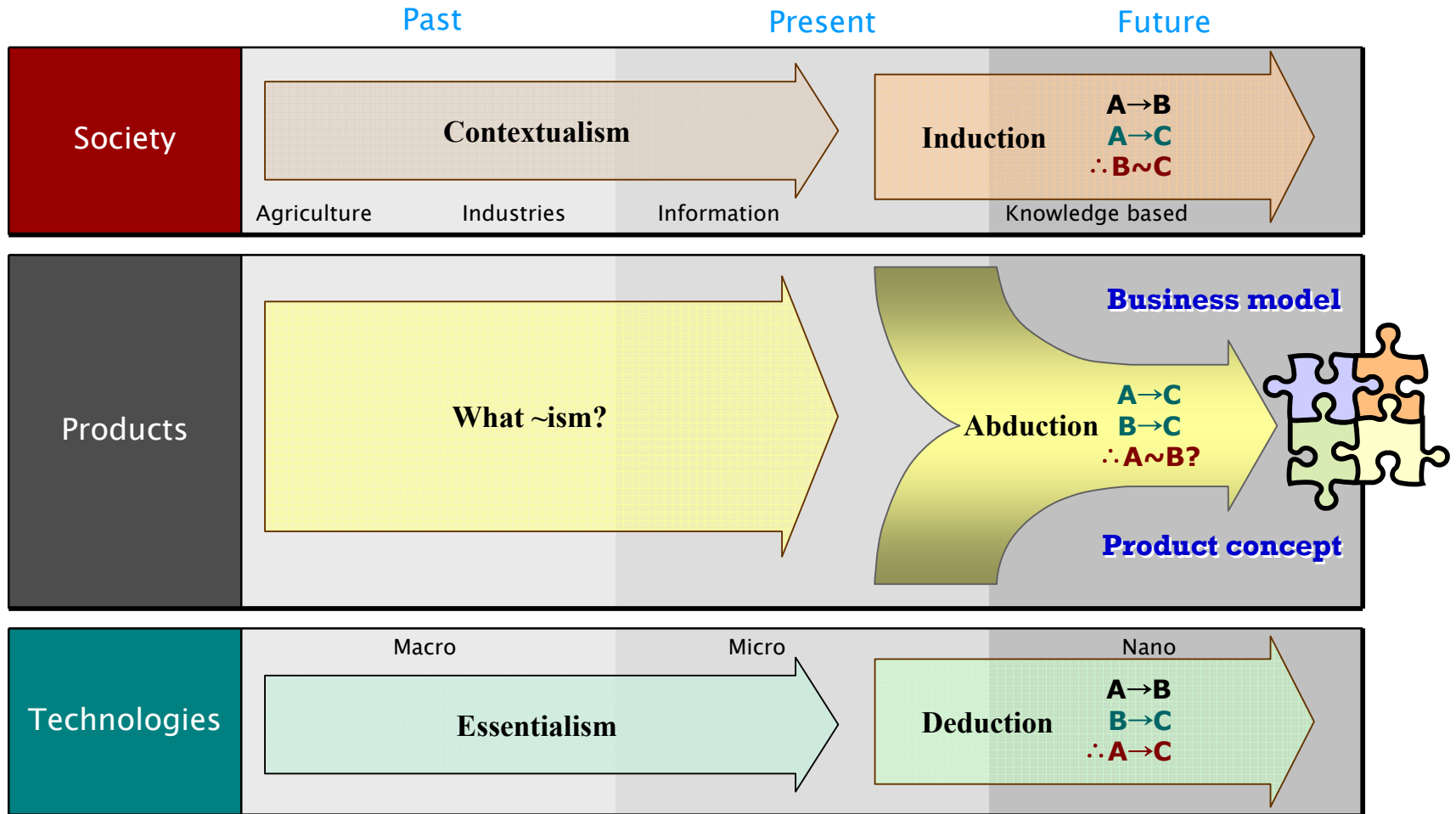
32G NAND



scaling down = segmentation

Can we forecast future products?

Ecosystem should be considered in addition to evolution pattern.
 Product concept and business model are neither induced nor deduced, but created.

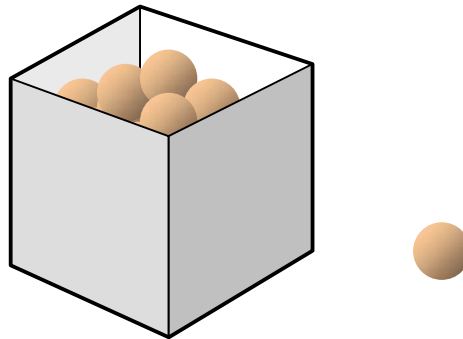


Why abduction?

Deduction : Knowledge is limited

Induction : The conclusion may be wrong

Abduction : Knowledge can be expanded



There are beads in the box on the table.

There is a bead on the table.

Thus,

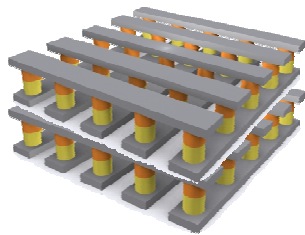
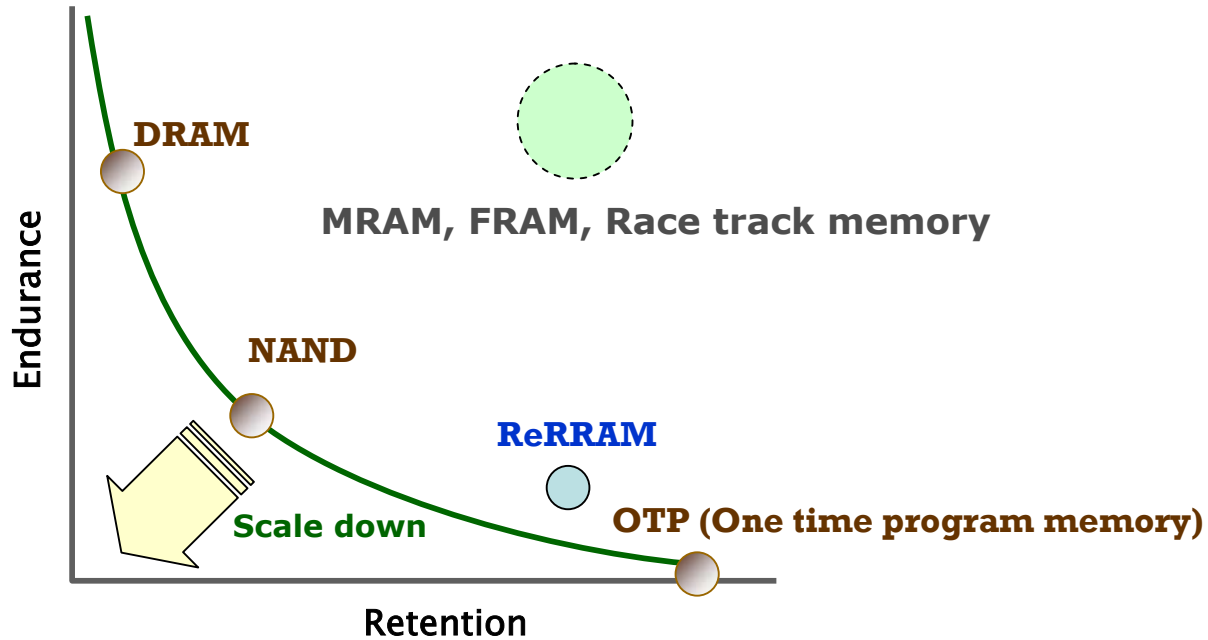
- 1) The bead might have come out from the box.
- 2) The bead might have been missed when putting beads in the box.
- 3) The bead might have been put on the table separately, etc..

Exercise : What is next? 2015, Global Business Network

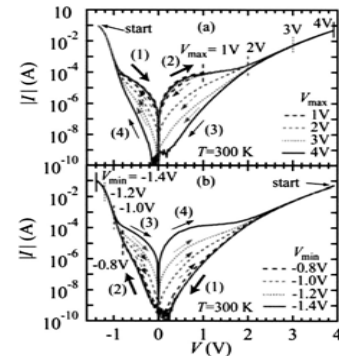
1. Find mega trend (Induction)
2. Forecast the final pattern (Abduction)
3. Verify the answer (Deduction)

| | | | | | | | | |
|----------|----------|----------|----------|----------|----------|----------|----------|----------|
| 1 | 1 | 2 | 3 | 3 | 1 | 2 | 3 | 3 |
| 2 | 3 | 1 | 1 | 3 | 2 | 2 | 1 | 1 |
| 2 | 3 | 3 | 2 | 2 | 1 | 1 | 3 | 2 |
| 3 | 1 | 2 | 3 | 1 | 2 | 3 | 1 | 2 |
| 3 | 1 | 3 | 3 | 2 | 1 | 1 | 3 | 3 |
| 2 | 2 | 1 | 1 | 3 | 2 | 2 | 1 | 2 |
| 2 | 3 | 2 | 2 | 1 | 3 | | | |
| 1 | 3 | 1 | 2 | 3 | 2 | | | |
| 3 | 1 | 2 | 3 | 1 | 1 | | | |

Deductive forecasting memory evolution



Stacked 1D1R ReRAM



Multi level ReRAM

Perspectives on ReRAM

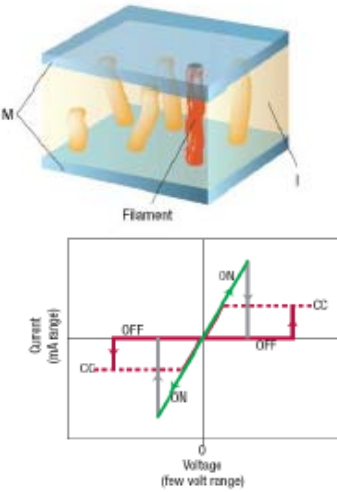
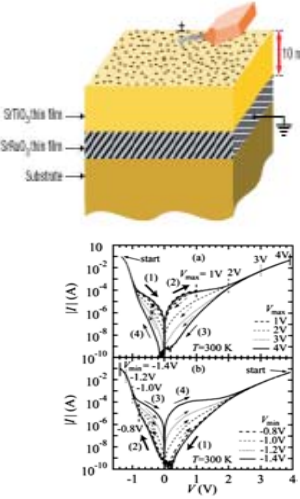
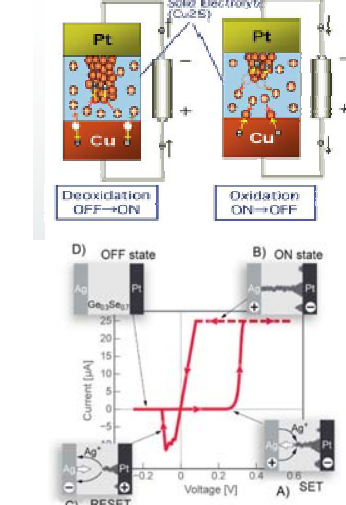
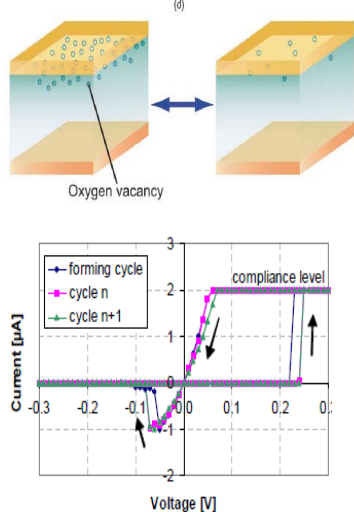
Applications:

- One time programmable memory for DRM.
- High capacity ReRAM with switching speed faster than NAND for 3D camera.
- Tunable resistor in analog logic for pattern recognition.

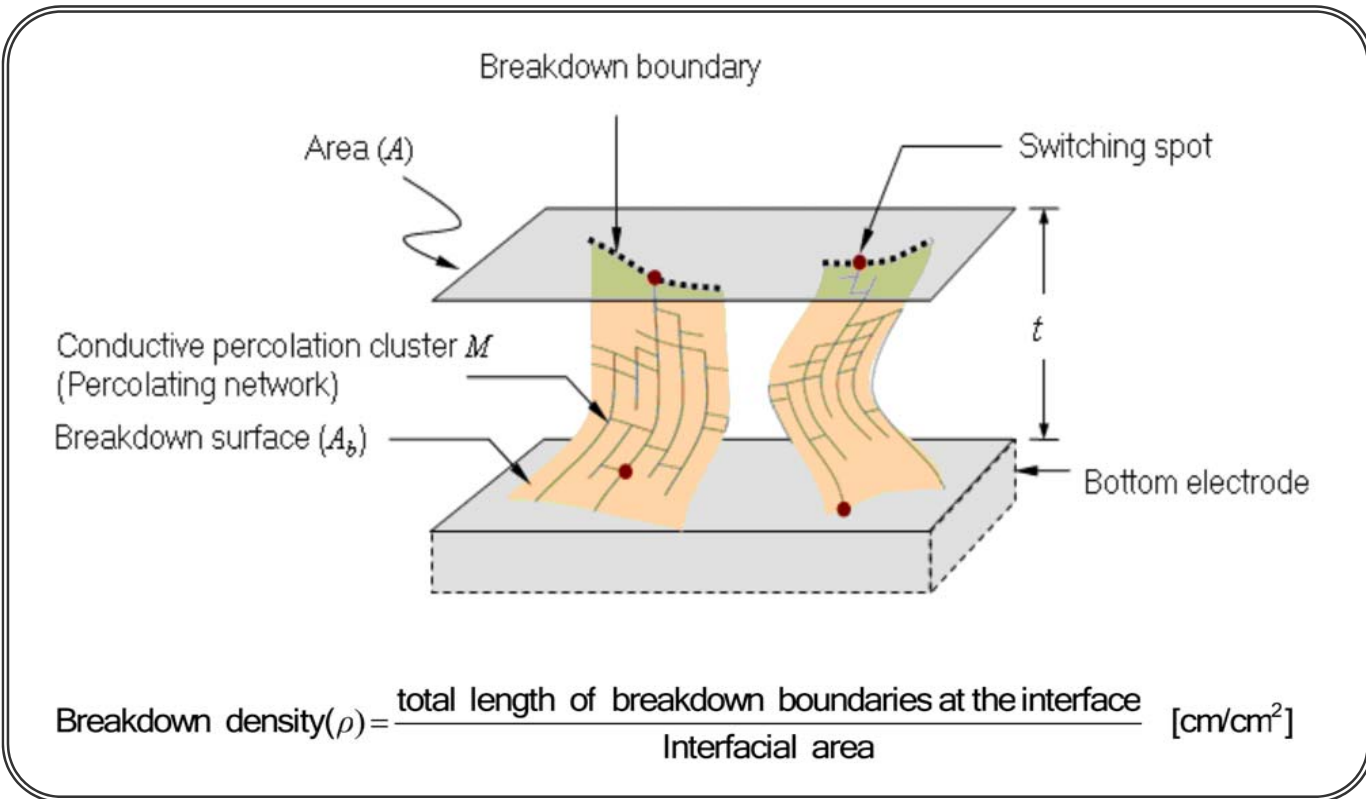
Required innovation:

- p^+i-n type ReRAM materials
- Multi-level ReRAM materials

Switching mechanisms in ReRAMs

| Fuse/Anti fuse memory switching | Electronic effect based switching | Metal ion motion based switching | Oxygen ion motion based switching |
|---|---|---|--|
|  <p>The diagram shows a crossbar array with a filament (orange) connecting two metal lines (blue). Below it, an I-V plot shows a non-linear, diode-like characteristic with a sharp increase in current at a certain voltage threshold, labeled as ON and OFF states.</p> |  <p>The diagram shows a layered structure with STO₂ thin film, SrRuO₃ thin film, and a substrate. Below it, two I-V plots (a) and (b) show non-linear characteristics with multiple states, labeled as OFF and ON states, and include parameters like P_{max} and V_{max}.</p> |  <p>The diagram shows Pt electrodes, a Solid Electrolyte (Cu₂Se), and Cu ions. It illustrates the process of Deposition (OFF → ON) and Oxidation (ON → OFF). Below it, an I-V plot shows a hysteresis loop with states labeled as OFF state, ON state, RESET, and SET.</p> |  <p>The diagram shows oxygen vacancies (blue circles) moving between two states. Below it, an I-V plot shows a hysteresis loop with states labeled as forming cycle, cycle n, and cycle n+1, and includes a compliance level.</p> |
| <ul style="list-style-type: none"> ▪ Unipolar switching with diode ▪ Excellent retention | <ul style="list-style-type: none"> ▪ Excellent uniformity ▪ Multilevel | <ul style="list-style-type: none"> ▪ Fast P/E speed ▪ Low power ▪ Multilevel | <ul style="list-style-type: none"> ▪ Fast P/E speed ▪ Excellent endurance ▪ Excellent statistical distribution ▪ Low power ▪ Multilevel |
| <ul style="list-style-type: none"> ▪ Need electro forming ▪ Poor uniformity | <ul style="list-style-type: none"> ▪ Poor retention ▪ Poor scalability | <ul style="list-style-type: none"> ▪ Need low temperature process ▪ Poor retention/poor uniformity | <ul style="list-style-type: none"> ▪ Poor retention |

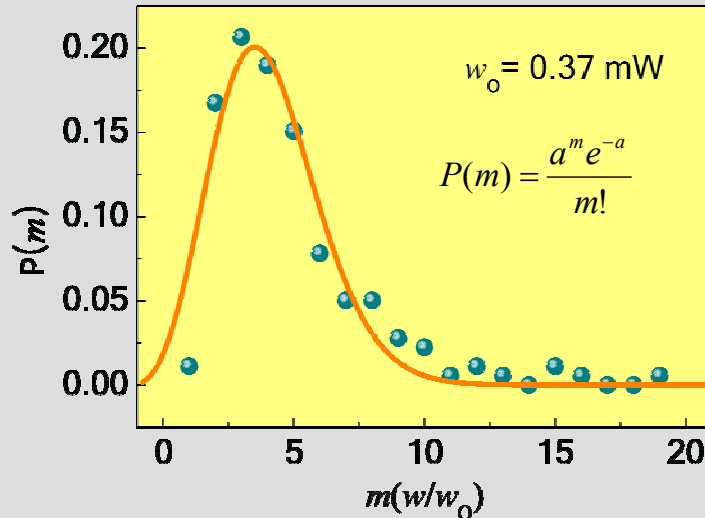
A switching mechanism in ReRAM



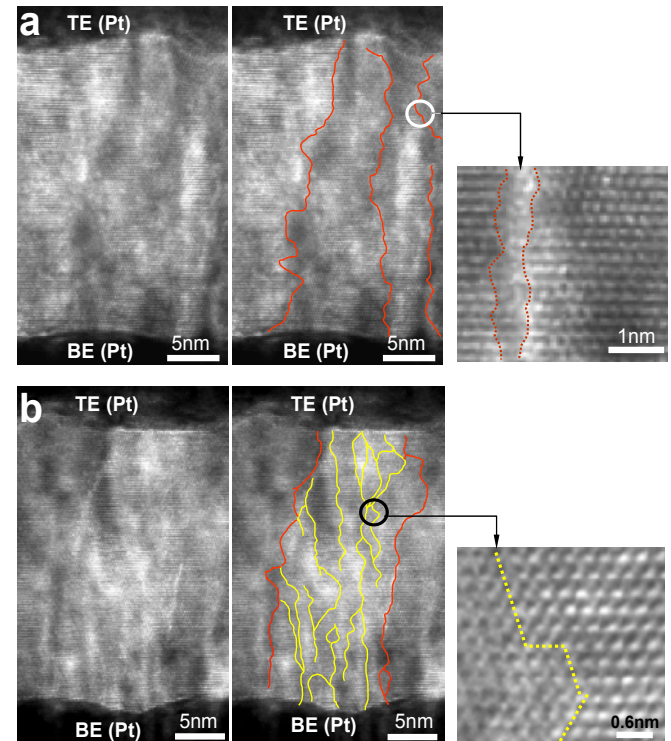
A percolation cluster model during resistance switching. The conducting cluster resides on the breakdown surface in the shape of a network. The main body of the cluster may not deform so much during switching. Instead, some spots in a percolating network may contribute to switching by connecting and disconnecting the cluster to the top and bottom electrodes. The cluster size is proportional to the electrode area in such a manner that

$$M \propto A_b^d = (\rho A \alpha t)^d$$

A switching mechanism in RRAM



Switching data distribution of NiO thin film. Four filaments are involved most frequently during reset (from "0" to "1") in the area of $30\mu\text{m} \times 30\mu\text{m}$.



$P(m)$: Probability density of either formation or breakage of chain of the conducting percolation cluster.

n : The total possible number of sites that can be involved in connecting clusters to the electrode.

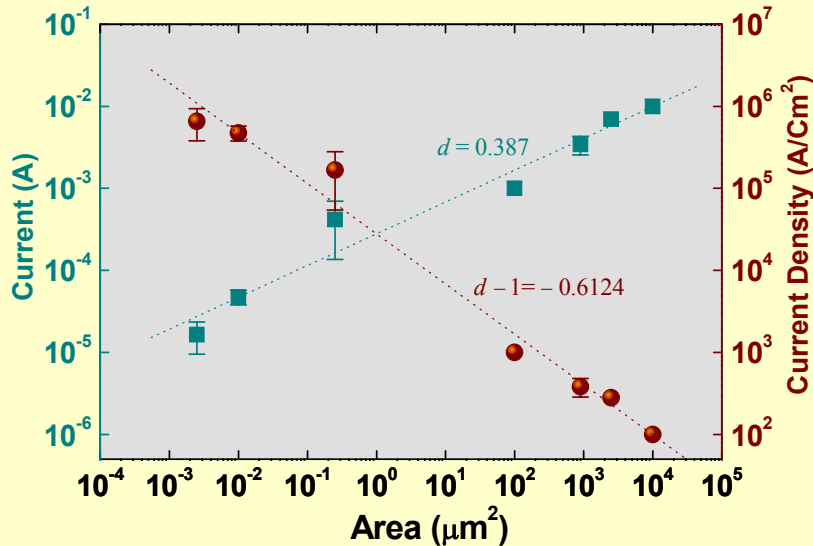
p : Probability of connecting spot formation.

m : The number of success to form connecting spots in area A .

s : Site density in area A . $a=np=sAp$

A switching mechanism in ReRAM

Fractals in ReRAM switching



Current versus electrode area at a conductive (reset) state.

$$M \propto A_b^d = (\rho A \alpha t)^d$$

$M(r) \propto r^D$, where $M(r)$ is the number of points in the sphere of radius r with fractal dimension D with $D < 2$. *

$$M(r) \propto A_b^{D/2}$$

and it is assumed that

$$m \propto \sqrt{M(r)},$$

then $m \propto A_b^{D/4} \propto A^{D/4}$.

Since $I \propto m \propto M \propto A^d$,

$$\ln I \cong d \ln A + \text{constant}$$

$$\ln J \cong (d - 1) \ln A + \text{constant}$$

, where $d = D/4$.

Thus, $d < 0.5$

*T. Nakayama and K. Yakubo, Fractal concepts in condensed matter physics, (Springer series in solid-state sciences, 2003).

Research suggestions on ReRAM

- **Business model and product concept for ReRAM can be created by evolution patterns.**
- **Chaos and complexity phenomena should be considered in ReRAM studies.**
- **Reconfigurable logic may be one of promising areas for ReRAM applications.**
- **Applications of oxide ReRAM materials can be expanded to transparent oxide electronics including transparent sensors.**